



Materials, Processes, Integration and Reliability in Advanced Interconnects for Micro- and Nanoelectronics: Volume 990: Symposium Held April 10-12, 2007, San Francisco, California, U.S.A. (Paperback)

By -

CAMBRIDGE UNIVERSITY PRESS, United Kingdom, 2014. Paperback. Condition: New. Language: English . Brand New Book ***** Print on Demand *****.In 2004, the microelectronics industry quietly ushered in the Nanoelectronics Era with the mass production of sub-100nm node devices. The current leading-edge semiconductor chips in mass production - the so-called 90nm node devices - have a transistor gate length of less than 50nm. This rapid technological advancement in the semiconductor industry has been made possible by innovations in materials employed in both transistor fabrication (front-end-of-the-line, FEOL) and interconnect fabrication (back-end-of-the-line, BEOL). The 90nm node BEOL features copper (Cu) interconnects and dielectric materials with a low-dielectric constant (k) of about 3.0. However, for the next generations of 65nm node and beyond, evolutionary and revolutionary innovations in BEOL materials and processes are needed to fuel the continued, healthy growth of the semiconductor. This book provides a forum to exchange advances in materials, processes, integration, and reliability in advanced interconnects and packaging. The book also addresses interconnects for emerging technologies, including 3D chip stacking and optical interconnects, as well as interconnects for optoelectronics, plastic electronics and molecular electronics.



READ ONLINE
[4.41 MB]

Reviews

Completely essential read book. It is one of the most remarkable publication i have got study. Once you begin to read the book, it is extremely difficult to leave it before concluding.

-- Santana Bogan

This pdf is great. I am quite late in start reading this one, but better then never. I am effortlessly can get a delight of looking at a composed publication.

-- Samara Hudson

You May Also Like



[Gypsy Breynton](#)

Echo Library. Paperback. Book Condition: New. Paperback. 88 pages. Dimensions: 9.0in. x 6.0in. x 0.2in.Hon. Gypsy Breynton, Esq. , M. A. , D. D. , LL. D. , C. , c. Gypsy Breynton, R, R. Tom was very proud of his handwriting....



[ESV Study Bible, Large Print \(Hardback\)](#)

CROSSWAY BOOKS, United States, 2014. Hardback. Book Condition: New. Large Print. 249 x 178 mm. Language: English . Brand New Book. The ESV Study Bible, Large Print edition transforms the content of the award-winning ESV Study Bible into a highly readable, large-print...



[ESV Study Bible, Large Print](#)

CROSSWAY BOOKS, United States, 2014. Leather / fine binding. Book Condition: New. Large Print. 257 x 190 mm. Language: English . Brand New Book. The ESV Study Bible, Large Print edition transforms the content of the award-winning ESV Study Bible into a...



[Memoirs of Robert Cary, Earl of Monmouth](#)

BiblioLife. Paperback. Book Condition: New. This item is printed on demand. Paperback. 142 pages. Dimensions: 8.0in. x 5.0in. x 0.3in.The Author of the Memoirs. The Memoirs here presented to the reader may be said to combine every interest which can attach to...



[Aeschylus](#)

BiblioLife. Paperback. Book Condition: New. This item is printed on demand. Paperback. 260 pages. Dimensions: 8.0in. x 5.0in. x 0.6in.This Translation of Aeschylus, an entirely new one, is designed as an Appendix to my edition of that Poet in the Bibliotheca...



[Portrait of a Marriage: V. Sackville-West and Harold Nicolson](#)

Atheneum. PAPERBACK. Book Condition: New. 0689705972 12+ Year Old paperback book-Never Read-may have light shelf or handling wear-has a price sticker or price written inside front or back cover-publishers mark-Good Copy- I ship FAST with FREE tracking!!!! * I am a reputable...